

Europe Flip Chip Market By Packaging Technology (2.5D IC, 3D IC, and 2D IC), By Bumping Technology (Copper Pillar, Gold Bumping, Solder Bumping and Others), By End User (Electronics, Industrial, IT & Telecom, Automotive, Healthcare & Life Sciences, Aerospace & Defense and Others), By Country, Industry Analysis and Forecast, 2020 - 2026

<https://marketpublishers.com/r/EC063F879F5BEN.html>

Date: July 2020

Pages: 106

Price: US\$ 1,500.00 (Single User License)

ID: EC063F879F5BEN

Abstracts

The Europe Flip Chip Market would witness market growth of 8% CAGR during the forecast period (2020-2026).

Flip chips deliver a wide variety of benefits relative to wire bond packaging, such as substrate durability, superior physical and thermal and electrical efficiency, fast speed and reliability. Recent advanced flip-chip prototypes are in development with as many as 5,908 bumps/chip at a pitch of 200- μ m and 1,500 bumps / chip at a pitch of 170- μ m in the area array configurations.

One of the reasons that has a significant effect on demand for flip technology is the strong availability of devices such as smartphones, smart warbles, laptops and other portable products. Flip chip technology is being used to develop current products, and flip chip market manufacturers are already investing in R&D to implement form factors in different ranges. For example, manufacturers such as Intel and Samsung electronics have made a series of promotions to reduce the form factor for portable devices.

Nevertheless, the high costs associated with the introduction of flip-chip technology and the existence of low customization options compared to wire bonding are expected to impede market growth to a large extent. The continuously declining size of digital

devices and the growing demand for mobile sensors are anticipated to be key trends in the flip-chip market during the forecast period.

Based on Packaging Technology, the market is segmented into 2.5D IC, 3D IC and 2D IC. Based on Bumping Technology, the market is segmented into Copper Pillar, Gold Bumping, Solder Bumping and Others. Based on End User, the market is segmented into Electronics, Industrial, IT & Telecom, Automotive, Healthcare & Life Sciences, Aerospace & Defense and Others. Based on countries, the market is segmented into Germany, UK, France, Russia, Spain, Italy, and Rest of Europe.

The market research report covers the analysis of key stake holders of the market. Key companies profiled in the report include 3M Company, Advanced Micro Devices, Inc., Amkor Technology, Inc., Apple, Inc., Fujitsu Limited, Intel Corporation, IBM Corporation, Samsung Electronics Co., Ltd., Texas Instruments, Inc., and Taiwan Semiconductor Manufacturing Company.

Scope of the Study

Market Segmentation:

By Packaging Technology

2.5D IC

3D IC

2D IC

By Bumping Technology

Copper Pillar

Gold Bumping

Solder Bumping

Others

By End User

Electronics

Industrial

IT & Telecom

Automotive

Healthcare & Life Sciences

Aerospace & Defense

Others

By Country

Germany

UK

France

Russia

Spain

Italy

Rest of Europe

Companies Profiled

3M Company

Advanced Micro Devices, Inc.

Amkor Technology, Inc.

Apple, Inc.

Fujitsu Limited

Intel Corporation

IBM Corporation

Samsung Electronics Co., Ltd.

Texas Instruments, Inc.

Taiwan Semiconductor Manufacturing Company

Unique Offerings from KBV Research

Exhaustive coverage

Highest number of market tables and figures

Subscription based model available

Guaranteed best price

Assured post sales research support with 10% customization free

Contents

CHAPTER 1. MARKET SCOPE & METHODOLOGY

- 1.1 Market Definition
- 1.2 Objectives
- 1.3 Market Scope
- 1.4 Segmentation
 - 1.4.1 Europe Flip Chip Market, by Packaging Technology
 - 1.4.2 Europe Flip Chip Market, by Bumping Technology
 - 1.4.3 Europe Flip Chip Market, by End User
 - 1.4.4 Europe Flip Chip Market, by Country
- 1.5 Methodology for the research

CHAPTER 2. MARKET OVERVIEW

- 2.1 Introduction
 - 2.1.1 Overview
 - 2.1.2 Executive Summary
 - 2.1.3 Market Composition and Scenario
- 2.2 Key Factors Impacting the Market
 - 2.2.1 Market Drivers
 - 2.2.2 Market Restraints

CHAPTER 3. EUROPE FLIP CHIP MARKET BY PACKAGING TECHNOLOGY

- 3.1 Europe Flip Chip 2.5D IC Market by Country
- 3.2 Europe Flip Chip 3D IC Market by Country
- 3.3 Europe Flip Chip 2D IC Market by Country

CHAPTER 4. EUROPE FLIP CHIP MARKET BY BUMPING TECHNOLOGY

- 4.1 Europe Copper Pillar Flip Chip Market by Country
- 4.2 Europe Gold Bumping Flip Chip Market by Country
- 4.3 Europe Solder Bumping Flip Chip Market by Country
- 4.4 Europe Other Bumping Technology Flip Chip Market by Country

CHAPTER 5. EUROPE FLIP CHIP MARKET BY END USER

- 5.1 Europe Electronics Flip Chip Market by Country
- 5.2 Europe Industrial Flip Chip Market by Country
- 5.3 Europe IT & Telecom Flip Chip Market by Country
- 5.4 Europe Automotive Flip Chip Market by Country
- 5.5 Europe Healthcare & Life Sciences Flip Chip Market by Country
- 5.6 Europe Aerospace & Defense Flip Chip Market by Country
- 5.7 Europe Others Flip Chip Market by Country

CHAPTER 6. EUROPE FLIP CHIP MARKET BY COUNTRY

- 6.1 Germany Flip Chip Market
 - 6.1.1 Germany Flip Chip Market by Packaging Technology
 - 6.1.2 Germany Flip Chip Market by Bumping Technology
 - 6.1.3 Germany Flip Chip Market by End User
- 6.2 UK Flip Chip Market
 - 6.2.1 UK Flip Chip Market by Packaging Technology
 - 6.2.2 UK Flip Chip Market by Bumping Technology
 - 6.2.3 UK Flip Chip Market by End User
- 6.3 France Flip Chip Market
 - 6.3.1 France Flip Chip Market by Packaging Technology
 - 6.3.2 France Flip Chip Market by Bumping Technology
 - 6.3.3 France Flip Chip Market by End User
- 6.4 Russia Flip Chip Market
 - 6.4.1 Russia Flip Chip Market by Packaging Technology
 - 6.4.2 Russia Flip Chip Market by Bumping Technology
 - 6.4.3 Russia Flip Chip Market by End User
- 6.5 Spain Flip Chip Market
 - 6.5.1 Spain Flip Chip Market by Packaging Technology
 - 6.5.2 Spain Flip Chip Market by Bumping Technology
 - 6.5.3 Spain Flip Chip Market by End User
- 6.6 Italy Flip Chip Market
 - 6.6.1 Italy Flip Chip Market by Packaging Technology
 - 6.6.2 Italy Flip Chip Market by Bumping Technology
 - 6.6.3 Italy Flip Chip Market by End User
- 6.7 Rest of Europe Flip Chip Market
 - 6.7.1 Rest of Europe Flip Chip Market by Packaging Technology
 - 6.7.2 Rest of Europe Flip Chip Market by Bumping Technology
 - 6.7.3 Rest of Europe Flip Chip Market by End User

CHAPTER 7. COMPANY PROFILES

7.1 3M Company

- 7.1.1 Company Overview
- 7.1.2 Financial Analysis
- 7.1.3 Segmental and Regional Analysis
- 7.1.4 Research & Development Expense
- 7.1.5 SWOT Analysis

7.2 Advanced Micro Devices, Inc.

- 7.2.1 Company Overview
- 7.2.2 Financial Analysis
- 7.2.3 Segmental and Regional Analysis
- 7.2.4 Research & Development Expenses

7.3 Amkor Technology, Inc.

- 7.3.1 Company Overview
- 7.3.2 Financial Analysis
- 7.3.3 Regional Analysis
- 7.3.4 Research & Development Expense
- 7.3.5 Recent strategies and developments:
 - 7.3.5.1 Partnerships, Collaborations, and Agreements:

7.4 Apple, Inc.

- 7.4.1 Company Overview
- 7.4.2 Financial Analysis
- 7.4.3 Product and Regional Analysis
- 7.4.4 Research & Development Expense
- 7.4.5 SWOT Analysis

7.5 Fujitsu Limited

- 7.5.1 Company Overview
- 7.5.2 Financial Analysis
- 7.5.3 SWOT Analysis

7.6 Intel Corporation

- 7.6.1 Company Overview
- 7.6.2 Financial Analysis
- 7.6.3 Segmental and Regional Analysis
- 7.6.4 Research & Development Expenses
- 7.6.5 Recent strategies and developments:
 - 7.6.5.1 Acquisition and Mergers:
- 7.6.6 SWOT Analysis

7.7 IBM Corporation

- 7.7.1 Company Overview
- 7.7.2 Financial Analysis
- 7.7.3 Regional & Segmental Analysis
- 7.7.4 Research & Development Expenses
- 7.7.5 SWOT Analysis
- 7.8 Samsung Electronics Co., Ltd. (Samsung Group)
 - 7.8.1 Company Overview
 - 7.8.2 Financial Analysis
 - 7.8.3 Segmental and Regional Analysis
 - 7.8.4 Research & Development Expense
 - 7.8.5 Recent strategies and developments:
 - 7.8.5.1 Product Launches and Product Expansions:
 - 7.8.6 SWOT Analysis
- 7.9 Texas Instruments, Inc.
 - 7.9.1 Company Overview
 - 7.9.2 Financial Analysis
 - 7.9.3 Segmental and Regional Analysis
 - 7.9.4 Research & Development Expense
 - 7.9.5 SWOT Analysis
- 7.1 Taiwan Semiconductor Manufacturing Company
 - 7.10.1 Company overview
 - 7.10.2 Financial Analysis
 - 7.10.3 Regional Analysis
 - 7.10.4 Research & Development Expense

List Of Tables

LIST OF TABLES

TABLE 1 EUROPE FLIP CHIP MARKET, 2016 - 2019, USD MILLION

TABLE 2 EUROPE FLIP CHIP MARKET, 2020 - 2026, USD MILLION

TABLE 3 EUROPE FLIP CHIP MARKET BY PACKAGING TECHNOLOGY, 2016 - 2019, USD MILLION

TABLE 4 EUROPE FLIP CHIP MARKET BY PACKAGING TECHNOLOGY, 2020 - 2026, USD MILLION

TABLE 5 EUROPE FLIP CHIP 2.5D IC MARKET BY COUNTRY, 2016 - 2019, USD MILLION

TABLE 6 EUROPE FLIP CHIP 2.5D IC MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 7 EUROPE FLIP CHIP 3D IC MARKET BY COUNTRY, 2016 - 2019, USD MILLION

TABLE 8 EUROPE FLIP CHIP 3D IC MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 9 EUROPE FLIP CHIP 2D IC MARKET BY COUNTRY, 2016 - 2019, USD MILLION

TABLE 10 EUROPE FLIP CHIP 2D IC MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 11 EUROPE FLIP CHIP MARKET BY BUMPING TECHNOLOGY, 2016 - 2019, USD MILLION

TABLE 12 EUROPE FLIP CHIP MARKET BY BUMPING TECHNOLOGY, 2020 - 2026, USD MILLION

TABLE 13 EUROPE COPPER PILLAR FLIP CHIP MARKET BY COUNTRY, 2016 - 2019, USD MILLION

TABLE 14 EUROPE COPPER PILLAR FLIP CHIP MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 15 EUROPE GOLD BUMPING FLIP CHIP MARKET BY COUNTRY, 2016 - 2019, USD MILLION

TABLE 16 EUROPE GOLD BUMPING FLIP CHIP MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 17 EUROPE SOLDER BUMPING FLIP CHIP MARKET BY COUNTRY, 2016 - 2019, USD MILLION

TABLE 18 EUROPE SOLDER BUMPING FLIP CHIP MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 19 EUROPE OTHER BUMPING TECHNOLOGY FLIP CHIP MARKET BY

Europe Flip Chip Market By Packaging Technology (2.5D IC, 3D IC, and 2D IC), By Bumping Technology (Copper Pil...

COUNTRY, 2016 - 2019, USD MILLION

TABLE 20 EUROPE OTHER BUMPING TECHNOLOGY FLIP CHIP MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 21 EUROPE FLIP CHIP MARKET BY END USER, 2016 - 2019, USD MILLION

TABLE 22 EUROPE FLIP CHIP MARKET BY END USER, 2020 - 2026, USD MILLION

TABLE 23 EUROPE ELECTRONICS FLIP CHIP MARKET BY COUNTRY, 2016 - 2019, USD MILLION

TABLE 24 EUROPE ELECTRONICS FLIP CHIP MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 25 EUROPE INDUSTRIAL FLIP CHIP MARKET BY COUNTRY, 2016 - 2019, USD MILLION

TABLE 26 EUROPE INDUSTRIAL FLIP CHIP MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 27 EUROPE IT & TELECOM FLIP CHIP MARKET BY COUNTRY, 2016 - 2019, USD MILLION

TABLE 28 EUROPE IT & TELECOM FLIP CHIP MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 29 EUROPE AUTOMOTIVE FLIP CHIP MARKET BY COUNTRY, 2016 - 2019, USD MILLION

TABLE 30 EUROPE AUTOMOTIVE FLIP CHIP MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 31 EUROPE HEALTHCARE & LIFE SCIENCES FLIP CHIP MARKET BY COUNTRY, 2016 - 2019, USD MILLION

TABLE 32 EUROPE HEALTHCARE & LIFE SCIENCES FLIP CHIP MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 33 EUROPE AEROSPACE & DEFENSE FLIP CHIP MARKET BY COUNTRY, 2016 - 2019, USD MILLION

TABLE 34 EUROPE AEROSPACE & DEFENSE FLIP CHIP MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 35 EUROPE OTHERS FLIP CHIP MARKET BY COUNTRY, 2016 - 2019, USD MILLION

TABLE 36 EUROPE OTHERS FLIP CHIP MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 37 EUROPE FLIP CHIP MARKET BY COUNTRY, 2016 - 2019, USD MILLION

TABLE 38 EUROPE FLIP CHIP MARKET BY COUNTRY, 2020 - 2026, USD MILLION

TABLE 39 GERMANY FLIP CHIP MARKET, 2016 - 2019, USD MILLION

TABLE 40 GERMANY FLIP CHIP MARKET, 2020 - 2026, USD MILLION

TABLE 41 GERMANY FLIP CHIP MARKET BY PACKAGING TECHNOLOGY, 2016 - 2019, USD MILLION

TABLE 42 GERMANY FLIP CHIP MARKET BY PACKAGING TECHNOLOGY, 2020 - 2026, USD MILLION

TABLE 43 GERMANY FLIP CHIP MARKET BY BUMPING TECHNOLOGY, 2016 - 2019, USD MILLION

TABLE 44 GERMANY FLIP CHIP MARKET BY BUMPING TECHNOLOGY, 2020 - 2026, USD MILLION

TABLE 45 GERMANY FLIP CHIP MARKET BY END USER, 2016 - 2019, USD MILLION

TABLE 46 GERMANY FLIP CHIP MARKET BY END USER, 2020 - 2026, USD MILLION

TABLE 47 UK FLIP CHIP MARKET, 2016 - 2019, USD MILLION

TABLE 48 UK FLIP CHIP MARKET, 2020 - 2026, USD MILLION

TABLE 49 UK FLIP CHIP MARKET BY PACKAGING TECHNOLOGY, 2016 - 2019, USD MILLION

TABLE 50 UK FLIP CHIP MARKET BY PACKAGING TECHNOLOGY, 2020 - 2026, USD MILLION

TABLE 51 UK FLIP CHIP MARKET BY BUMPING TECHNOLOGY, 2016 - 2019, USD MILLION

TABLE 52 UK FLIP CHIP MARKET BY BUMPING TECHNOLOGY, 2020 - 2026, USD MILLION

TABLE 53 UK FLIP CHIP MARKET BY END USER, 2016 - 2019, USD MILLION

TABLE 54 UK FLIP CHIP MARKET BY END USER, 2020 - 2026, USD MILLION

TABLE 55 FRANCE FLIP CHIP MARKET, 2016 - 2019, USD MILLION

TABLE 56 FRANCE FLIP CHIP MARKET, 2020 - 2026, USD MILLION

TABLE 57 FRANCE FLIP CHIP MARKET BY PACKAGING TECHNOLOGY, 2016 - 2019, USD MILLION

TABLE 58 FRANCE FLIP CHIP MARKET BY PACKAGING TECHNOLOGY, 2020 - 2026, USD MILLION

TABLE 59 FRANCE FLIP CHIP MARKET BY BUMPING TECHNOLOGY, 2016 - 2019, USD MILLION

TABLE 60 FRANCE FLIP CHIP MARKET BY BUMPING TECHNOLOGY, 2020 - 2026, USD MILLION

TABLE 61 FRANCE FLIP CHIP MARKET BY END USER, 2016 - 2019, USD MILLION

TABLE 62 FRANCE FLIP CHIP MARKET BY END USER, 2020 - 2026, USD MILLION

TABLE 63 RUSSIA FLIP CHIP MARKET, 2016 - 2019, USD MILLION

TABLE 64 RUSSIA FLIP CHIP MARKET, 2020 - 2026, USD MILLION

TABLE 65 RUSSIA FLIP CHIP MARKET BY PACKAGING TECHNOLOGY, 2016 - 2019, USD MILLION

TABLE 66 RUSSIA FLIP CHIP MARKET BY PACKAGING TECHNOLOGY, 2020 -

2026, USD MILLION

TABLE 67 RUSSIA FLIP CHIP MARKET BY BUMPING TECHNOLOGY, 2016 - 2019, USD MILLION

TABLE 68 RUSSIA FLIP CHIP MARKET BY BUMPING TECHNOLOGY, 2020 - 2026, USD MILLION

TABLE 69 RUSSIA FLIP CHIP MARKET BY END USER, 2016 - 2019, USD MILLION

TABLE 70 RUSSIA FLIP CHIP MARKET BY END USER, 2020 - 2026, USD MILLION

TABLE 71 SPAIN FLIP CHIP MARKET, 2016 - 2019, USD MILLION

TABLE 72 SPAIN FLIP CHIP MARKET, 2020 - 2026, USD MILLION

TABLE 73 SPAIN FLIP CHIP MARKET BY PACKAGING TECHNOLOGY, 2016 - 2019, USD MILLION

TABLE 74 SPAIN FLIP CHIP MARKET BY PACKAGING TECHNOLOGY, 2020 - 2026, USD MILLION

TABLE 75 SPAIN FLIP CHIP MARKET BY BUMPING TECHNOLOGY, 2016 - 2019, USD MILLION

TABLE 76 SPAIN FLIP CHIP MARKET BY BUMPING TECHNOLOGY, 2020 - 2026, USD MILLION

TABLE 77 SPAIN FLIP CHIP MARKET BY END USER, 2016 - 2019, USD MILLION

TABLE 78 SPAIN FLIP CHIP MARKET BY END USER, 2020 - 2026, USD MILLION

TABLE 79 ITALY FLIP CHIP MARKET, 2016 - 2019, USD MILLION

TABLE 80 ITALY FLIP CHIP MARKET, 2020 - 2026, USD MILLION

TABLE 81 ITALY FLIP CHIP MARKET BY PACKAGING TECHNOLOGY, 2016 - 2019, USD MILLION

TABLE 82 ITALY FLIP CHIP MARKET BY PACKAGING TECHNOLOGY, 2020 - 2026, USD MILLION

TABLE 83 ITALY FLIP CHIP MARKET BY BUMPING TECHNOLOGY, 2016 - 2019, USD MILLION

TABLE 84 ITALY FLIP CHIP MARKET BY BUMPING TECHNOLOGY, 2020 - 2026, USD MILLION

TABLE 85 ITALY FLIP CHIP MARKET BY END USER, 2016 - 2019, USD MILLION

TABLE 86 ITALY FLIP CHIP MARKET BY END USER, 2020 - 2026, USD MILLION

TABLE 87 REST OF EUROPE FLIP CHIP MARKET, 2016 - 2019, USD MILLION

TABLE 88 REST OF EUROPE FLIP CHIP MARKET, 2020 - 2026, USD MILLION

TABLE 89 REST OF EUROPE FLIP CHIP MARKET BY PACKAGING TECHNOLOGY, 2016 - 2019, USD MILLION

TABLE 90 REST OF EUROPE FLIP CHIP MARKET BY PACKAGING TECHNOLOGY, 2020 - 2026, USD MILLION

TABLE 91 REST OF EUROPE FLIP CHIP MARKET BY BUMPING TECHNOLOGY, 2016 - 2019, USD MILLION

TABLE 92 REST OF EUROPE FLIP CHIP MARKET BY BUMPING TECHNOLOGY,
2020 - 2026, USD MILLION

TABLE 93 REST OF EUROPE FLIP CHIP MARKET BY END USER, 2016 - 2019, USD
MILLION

TABLE 94 REST OF EUROPE FLIP CHIP MARKET BY END USER, 2020 - 2026, USD
MILLION

TABLE 95 KEY INFORMATION – 3M COMPANY

TABLE 96 KEY INFORMATION – ADVANCED MICRO DEVICES, INC.

TABLE 97 KEY INFORMATION – AMKOR TECHNOLOGY, INC.

TABLE 98 KEY INFORMATION – APPLE, INC.

TABLE 99 KEY INFORMATION – FUJITSU LIMITED

TABLE 100 KEY INFORMATION – INTEL CORPORATION

TABLE 101 KEY INFORMATION – IBM CORPORATION

TABLE 102 KEY INFORMATION –SAMSUNG ELECTRONICS CO., LTD.

TABLE 103 KEY INFORMATION – TEXAS INSTRUMENTS, INC.

TABLE 104 KEY INFORMATION–TAIWAN SEMICONDUCTOR MANUFACTURING
COMPANY

List Of Figures

LIST OF FIGURES

FIG 1 METHODOLOGY FOR THE RESEARCH

FIG 2 SWOT ANALYSIS: 3M COMPANY

FIG 3 SWOT ANALYSIS: APPLE, INC.

FIG 4 SWOT ANALYSIS: FUJITSU LIMITED

FIG 5 SWOT ANALYSIS: INTEL CORPORATION

FIG 6 SWOT ANALYSIS: IBM CORPORATION

FIG 7 SWOT ANALYSIS: SAMSUNG ELECTRONICS CO. LTD.

FIG 8 SWOT ANALYSIS: TEXAS INSTRUMENTS, INC.

I would like to order

Product name: Europe Flip Chip Market By Packaging Technology (2.5D IC, 3D IC, and 2D IC), By Bumping Technology (Copper Pillar, Gold Bumping, Solder Bumping and Others), By End User (Electronics, Industrial, IT & Telecom, Automotive, Healthcare & Life Sciences, Aerospace & Defense and Others), By Country, Industry Analysis and Forecast, 2020 - 2026

Product link: <https://marketpublishers.com/r/EC063F879F5BEN.html>

Price: US\$ 1,500.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/EC063F879F5BEN.html>

To pay by Wire Transfer, please, fill in your contact details in the form below:

First name:
Last name:
Email:
Company:
Address:
City:
Zip code:
Country:
Tel:
Fax:
Your message:

****All fields are required**

Customer signature _____

Please, note that by ordering from marketpublishers.com you are agreeing to our Terms & Conditions at <https://marketpublishers.com/docs/terms.html>

To place an order via fax simply print this form, fill in the information below
and fax the completed form to +44 20 7900 3970